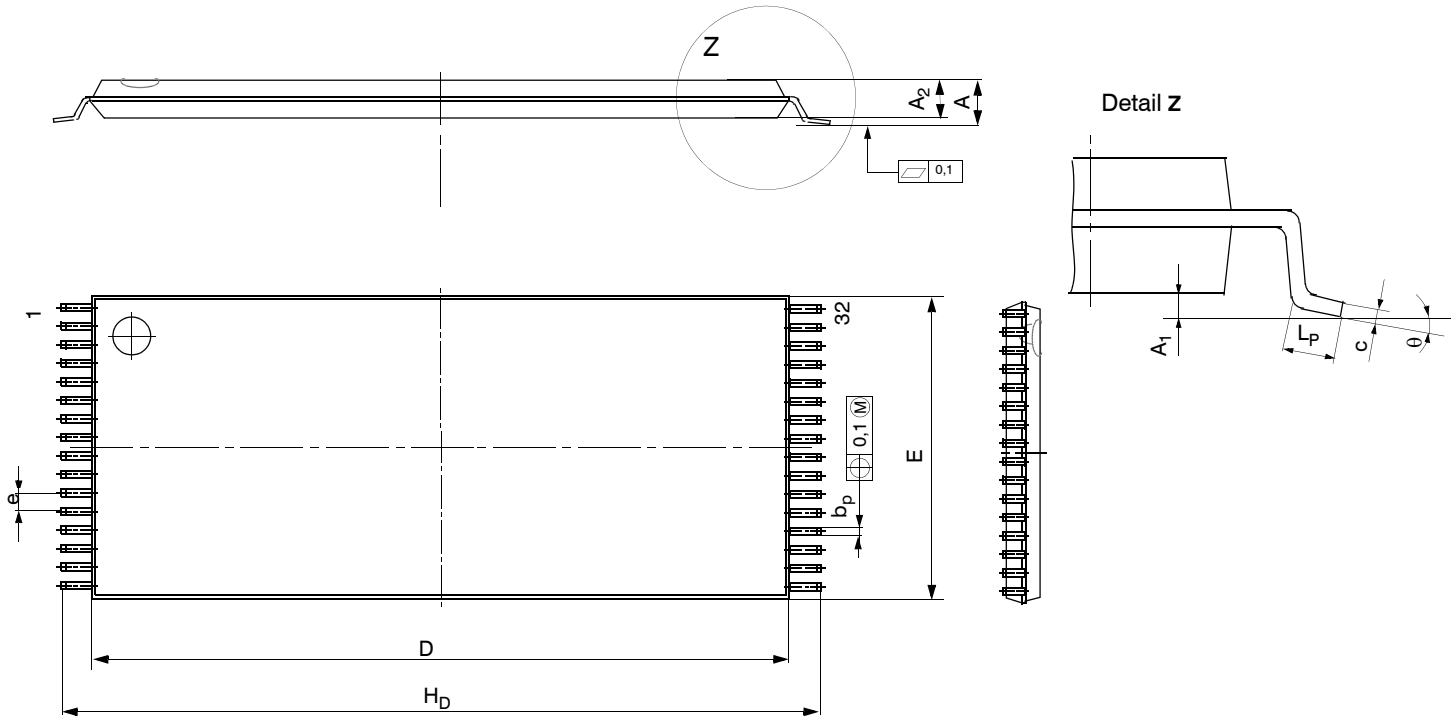
	<b>Package TSOP32 (1/8x20)</b> (Normal Option)	<b>MDS</b> <b>751</b>
---	---	--------------------------

Dimensions in millimetres

Based on JEDEC: JEP95 MO-142

**1 Dimensions**

Dimensions of Sub-Group B1	
$A_{max}$	1,20
$b_{Pmin}$	0,17
$b_{Pmax}$	0,27
$e_{nom}$	0,50
$H_{Dmin}$	19,80
$H_{Dmax}$	20,20
$L_{Pmin}$	0,40

- 2 Weight**  $\leq 0,3$  g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

Dimensions of Sub-Group C1	
$A_{min}$	-
$A_{1min}$	0,05
$A_{1max}$	0,15
$A_{2min}$	0,90
$A_{2max}$	1,05
$c_{min}$	0,10
$c_{max}$	0,21
$D_{min}^*$	18,30
$D_{max}^*$	18,50
$E_{min}^*$	7,80
$E_{max}^*$	8,20
$\theta_{min}$	0°
$\theta_{max}$	5°

\* without mold-flash

Zentrum Mikroelektronik Dresden		
Editor: signature by Schoder	Date: 07.12.2004	Doc-No. QS-000751-HD-02
Check: signature by Marx	Quality: signature by Tina Kochan	